

Data sheet Product ICK S R 32,5 x 30



Heatsinks and active heatsinks for processors>Pin heatsinks

Ø 32.5 x 30 mm, pin heatsinks round

Features

design:	round
way of fixation:	• therm. conductive foil • therm. cond. adhesive
socket:	universal
suitable for processor type:	universal
diameter:	32.5 mm
height:	30 mm
plate thickness:	3.5 mm
weight:	20.6 g
thermal resistance:	8.8 - 1.6 K/W
dissipation loss:	6.82 W
surface:	Al-natural

Technical Drawing

